



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IPD033N06N	<b>Issued</b>	12. May 2021
<b>MA#</b>	MA001709508		
<b>Package</b>	PG-TO252-3-313	<b>Weight*</b>	318.91 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.427	0.45	0.45	4475	4475
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		462	
	non noble metal	copper	7440-50-8	147.096	46.14	46.20	461244	461845
wire	non noble metal	aluminium	7429-90-5	5.658	1.77	1.77	17740	17740
encapsulation	inorganic material	zinc oxide	1314-13-2	1.387	0.43		4348	
	miscellaneous	miscellaneous	-	6.933	2.17		21740	
	plastics	epoxy resin	-	20.799	6.52		65219	
	inorganic material	silicon dioxide	60676-86-0	109.543	34.35	43.47	343489	434796
lead finish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11728	11728
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4454	4465
solder	non noble metal	tin	7440-31-5	0.030	0.01		95	
	noble metal	silver	7440-22-4	0.038	0.01		118	
	non noble metal	lead	7439-92-1	1.443	0.45	0.47	4526	4739
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.01	6.02	60134	60212
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com